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(54) Title: METHODS OF MANUFACTURING A LIGHT-EMITTING DEVICE WITH METAL INLAY AND TOP CONTACTS

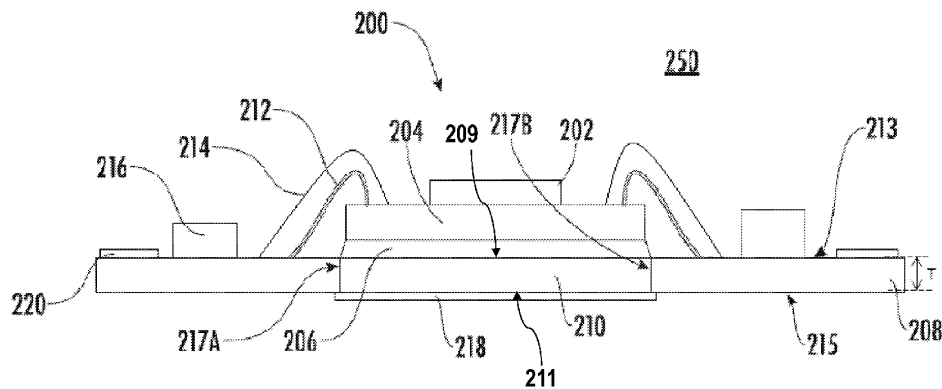


FIG. 2B

(57) Abstract: Methods of manufacturing light-emitting devices are described herein. A method includes obtaining a packaging substrate comprising an embedded metal inlay and a plurality of first contacts on a top surface of the packaging substrate, forming a hybridized device, attaching a bottom surface of the hybridized device to a top surface of the metal inlay, and wirebonding a top surface of the hybridized device to a top surface of the packaging substrate using a plurality of conductive connectors.

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